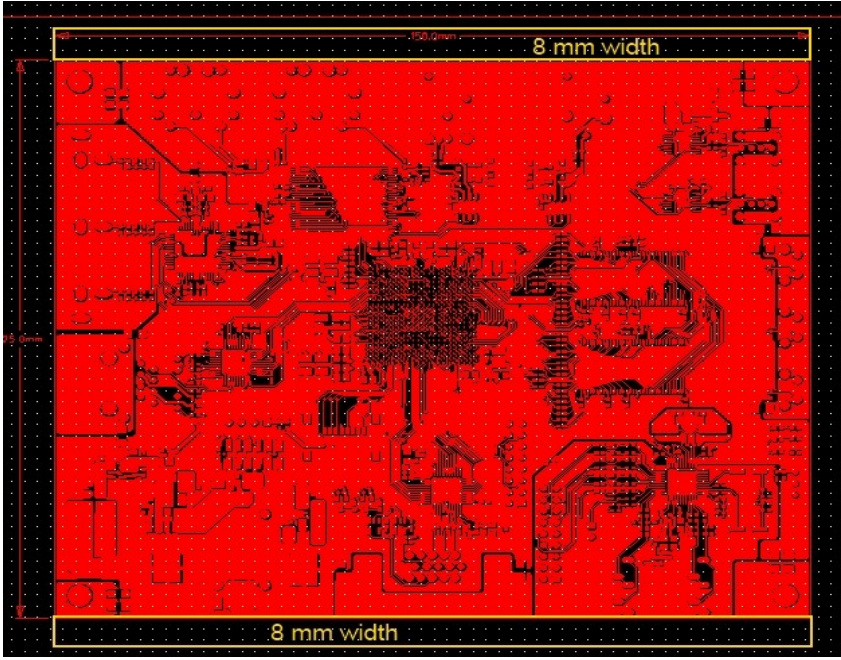




































# PCB Engineering Check List

Prepared on : 2010 / 11 / 08

Gerber File Name : 20101008_rc2_gerber.rar		File Size : 1.05M-bytes
P/N :		Used Model : Milkymist One
		Version : RC2
<b>PCB Spec.</b>	P.C.B dimension Long : _____mm ; Width : _____mm $\pm 0.05$ mm ; ●referred to gerber file	
<b>PCB 規格</b>	Material : ●FR4 ○CEM-3 ○others : _____; PCB thickness : _____1.6_____mm $\pm 0.1$ mm	
	Layers : ○single layer ○two layers ○four layers ●six layers ○eight layers ○ten layers	
	Copper Thickness (銅薄厚度) : ○1oz ○2oz ● others : 請見 stack-up 圖示	
	Surface Treatment (電鍍條件) : ○ Gold Plating (鍍金) ● Immersion Gold (化金) ○ HASL (噴錫) ○ Immersion Tin(鍍錫)	
	Immersion Gold Thickness (化金厚度) : ○ 2u ●3u ○ 5u	
	Solder resistant /Solder Mask (防焊油墨) : ○ Normal 傳統 ●Liquid ○Dryfilm	
	Solder Mask Color(防焊漆顏色) : ○ green ○ red ○ blue ● black 霧面 ○ dark brown ●two sides	
	Via – Mask : ○No Solder Mask(無防焊) ●Solder Mask(防焊), Solder Mask in 100% Plug Hole (請使用防焊漆作 100%全塞孔,)	
	Silk Text Color(文字顏色) : ●White(白漆) ●two sides ○others(其他) : _____	
	Panel (PCB 是否需製作連片) : ○ yes ● no	
	100% Open / Short Test : ● yes ○ no	
	<b>Delivery Criteria</b>	01. Please use solder mask to do 100% Plug Hole. Via – Mask 請使用防焊漆作 100%全塞孔。
<b>交貨需求</b>	02. Please add Optical FiducialMark. 需加光學定位點。	
	03. The V-Cut must exactly correct in specification. 板上的 V-Cut 請務必於交貨前確實地裁切完整。	
	04. Micro Section Inspection for Via hole/copper/plating/thickness. 微切片檢驗。	
	05. Materials must meet to RoHS compliant. 材料安全需證明符合歐盟 RoHS 規範。	
	06. The films must be delivered with PCB. 隨 P.C.B 回件附上底片。	
	07. Marking [UL] logo and Data Code for recognition. PCB 上需標示貴廠之「UL」商標及種類，加註 Date Code 和批號以茲區別。	

<b>Quotation in Demand</b>  報價	● <u>ProtoType/Sample Quotation</u> 樣品報價：  Quantity 樣品需求：● <u>50</u> pcs ● <u>2</u> pcs of RD Solderability samples ○ _____ pcs of PNL  Sample Price 樣品價格： _____  Expected PCB Return Date 回件日期： <u>2010 / 11 / 19</u>	○ <u>Small / Large Quotation</u> 量產報價：  Quantity 報價數量：_____ ○PCS ○PNL  Engineering Fee( Includes Film)工程費用(含底片)： _____  Test Fee( Includes Fixture) 測試費用(含治具)： _____  Panel Fee 板材費用： _____  Working Date 工作天數： _____
<b>Attached Files</b>  附件資料	○ Mechanical File (File Name：；bytes) or 機構圖 _____張  ● <u>V-Cut &amp; Supporter illustration file</u> (見下圖)，於上下增加各 8mm 需要 V-cut 的板邊。  	

	<p>●Recommended Stack-Up, 壓合疊構建議方式</p> <table border="1" data-bbox="486 257 1318 864"> <thead> <tr> <th>Stack-Up</th> <th></th> <th>建議PCB Stack(mil)</th> </tr> </thead> <tbody> <tr> <td>Solder mask</td> <td></td> <td>1</td> </tr> <tr> <td>L1</td> <td></td> <td>Copper+plating 1.7</td> </tr> <tr> <td></td> <td></td> <td>P.P. 4</td> </tr> <tr> <td>L2</td> <td></td> <td>Copper 1.4</td> </tr> <tr> <td></td> <td></td> <td>CORE 18</td> </tr> <tr> <td>L3</td> <td></td> <td>Copper 1.4</td> </tr> <tr> <td></td> <td></td> <td>P.P. 7</td> </tr> <tr> <td>L4</td> <td></td> <td>Copper 1.4</td> </tr> <tr> <td></td> <td></td> <td>CORE 18</td> </tr> <tr> <td>L5</td> <td></td> <td>Copper 1.4</td> </tr> <tr> <td></td> <td></td> <td>P.P. 4</td> </tr> <tr> <td>L6</td> <td></td> <td>Copper+plating 1.7</td> </tr> <tr> <td>Solder mask</td> <td></td> <td>1</td> </tr> <tr> <td colspan="2">Total</td> <td>62</td> </tr> </tbody> </table>					Stack-Up		建議PCB Stack(mil)	Solder mask		1	L1		Copper+plating 1.7			P.P. 4	L2		Copper 1.4			CORE 18	L3		Copper 1.4			P.P. 7	L4		Copper 1.4			CORE 18	L5		Copper 1.4			P.P. 4	L6		Copper+plating 1.7	Solder mask		1	Total		62
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<b>Package</b> 包 裝	<ol style="list-style-type: none"> <li>The part number and description should be same as our order information and correct.料號、品名規格之填寫以本公司採購單為憑，且力求清晰。</li> <li>The plastic bag must be sealed well in all envelopes. Please package 10 pcs in one bag lot. No any split condition in any corner or envelope of package while lifting any corner.塑膠袋封口需牢固，以 10pcs 為一小包裝且於任何一角提起，封口處均不可裂開。</li> <li>Each single package should mark part number and quantity, no collision damage will occurred among those packages.每小包裝請註明「料號」、「數量」且包裝方式不可有撞擊造成之危險。</li> </ol>																																																	
<b>Notes</b> 備 註	<ol style="list-style-type: none"> <li>Must have another one package with 2 pcs for RD sample use.包裝要有另一袋 2pcs 的包裝，RD 樣品用(試錫板與其他用途)。</li> <li>The supporter please produce it as small square pad as well.聯板支撐架請洗小方格 pad。</li> <li>The Film must be delivered back for acceptance process.PCB 板送洗回來請採購必須附上底片，否則會無法驗收。</li> </ol>																																																	
<b>Issued Despartme nt</b> 發行單位	Production Department	Applicant 申請人	 Adam Wang 王震龍	Vendor Signature																																														

Please vendor confirm above engineering items correctly and signature back by email (\*廠商若確認無誤請於當日簽名回傳\*)